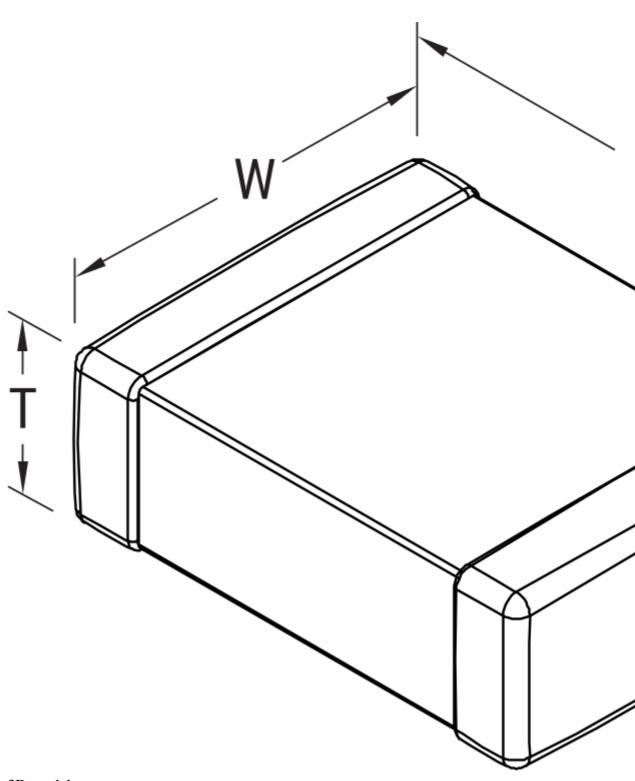
## C1206C300F3GACTU

## Aliases (C1206C300F3GAC7800)

SMD Comm C0G, Ceramic, 30 pF, 1%, 25 VDC, C0G, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1206



Click here for the 3D model.

**Dimensions** 

Chip Size 1206

L 3.2mm +/-0.2mm

#### **Dimensions**

W 1.6mm +/-0.2mm T 0.78mm +/-0.10mm B 0.5mm +/-0.25mm

#### **Packaging Specifications**

Packaging T&R, 180mm, Plastic Tape

Packaging Quantity 4000

#### **General Information**

Series SMD Comm C0G

Style SMD Chip

Description SMD, MLCC, Ultra-Stable, Low Loss, Class I

Features Ultra-Stable, Low Loss, Class I

RoHS Yes
Termination Tin
Marking No
AEC-Q200 No
Component Weight 15 mg
Shelf Life 78 Weeks

MSL 1

#### **Specifications**

Capacitance 30 pF

Measurement Condition 1 MHz 1.0Vrms

Capacitance Tolerance 1%

Voltage DC 25 VDC
Dielectric Withstanding Voltage 62.5 VDC
Temperature Range -55/+125°C

Temperature Coefficient COG

Capacitance Change with Reference to +25°C and 0 VDC 30 ppm/C, 1MegaHz

Applied (TCC) 1.0Vrms

Dissipation Factor 0.1% 1 MHz 1.0Vrms
Aging Rate 0% Loss/Decade Hour

Insulation Resistance 100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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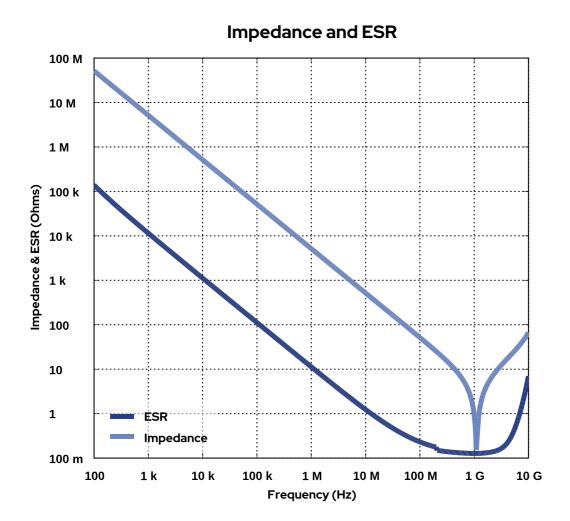
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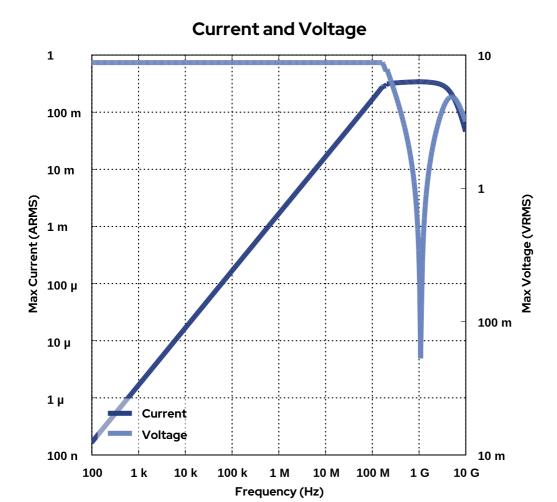
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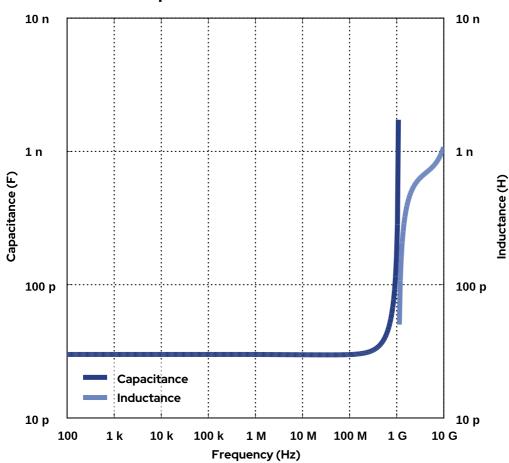
# **Simulations**

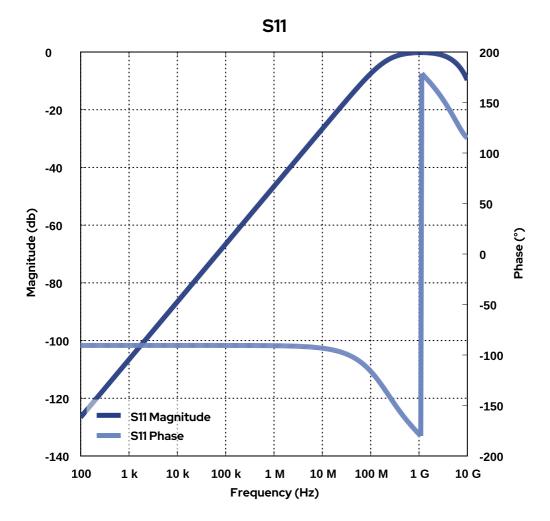
For the complete simulation environment please visit  $\underline{\text{K-SIM}}$ .

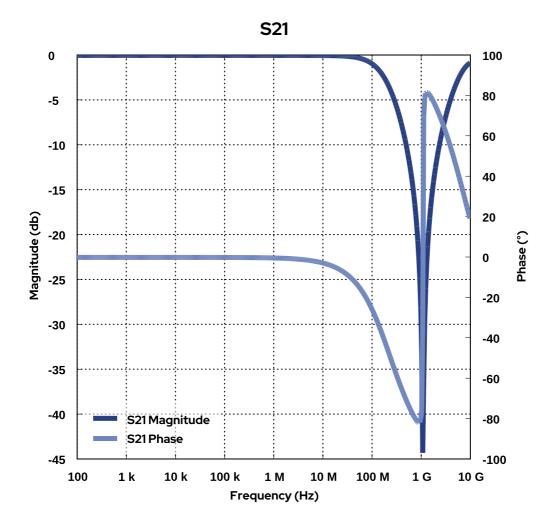




### Capacitance and Inductance







#### These are simulations.

#### This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are

- calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.